

Title (en)

Equipment and method for covering a metallic element with a layer of copper

Title (de)

Ausrüstung und Verfahren zum Bedecken eines metallischen Elements mit einer Kupferschicht

Title (fr)

Equipement et procédé pour couvrir un element métallique avec une couche de cuivre

Publication

EP 1207219 A1 20020522 (EN)

Application

EP 00830763 A 20001120

Priority

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Abstract (en)

Equipment and method for covering a metallic element with a layer of copper in which the said equipment comprises an electrodeposition tank and a dissolving tank; in its turn said dissolving tank includes a first section containing an anolyte, a second section containing a catholyte, and an interposed element placed between said first and said second sections and consisting of a porous diaphragm whose permeability to copper ions is so low that the quantity of copper ions migrating from said first section to said second section of said dissolving tank is equal to 0.01-5%/hour; and in which the ratio between cathode current density and anode current density in said dissolving tank is equal to at least 30 (Fig. 1). <IMAGE>

IPC 1-7

C25D 7/06; **C25D 21/14**

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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Citation (examination)

EP 0550002 A1 19930707 - NIPPON KOKAN KK [JP]

Designated contracting state (EPC)

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